

**Notice of References Cited**

Application/Contr

09/875,698

Applicant(s)/Patent Under  
Reexamination  
PYO, SUNG GYU

Examiner

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Art Unit

1765

Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6323121 B1	11-2001	Liu et al.	438/633
	B	US-RE 35614	09-1997	Norman et al.	427/250
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
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	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Koh et al. "Method of Forming Copper Interconnections and Thin Films Using Chemical Vapor Deposition with Catalyst," September 6, 2001, USPub. No. : US 2001/0019891 A1, 18..
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.